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ABSTRACT OF THE DISCLOSURE

A semiconductor chip has a plurality of front protruding electrodes and a plurality of rear film electrodes. The front electrodes are connected to interconnect lines made of a metallic film. The semiconductor chip is mounted on a printed circuit board by mounting the rear film electrodes on respective terminals of the printed circuit board and the metallic film is connected to other terminals of the printed circuit board by bonding wires. A large number of semiconductor chips can be fabricated in a simple process at a time.

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